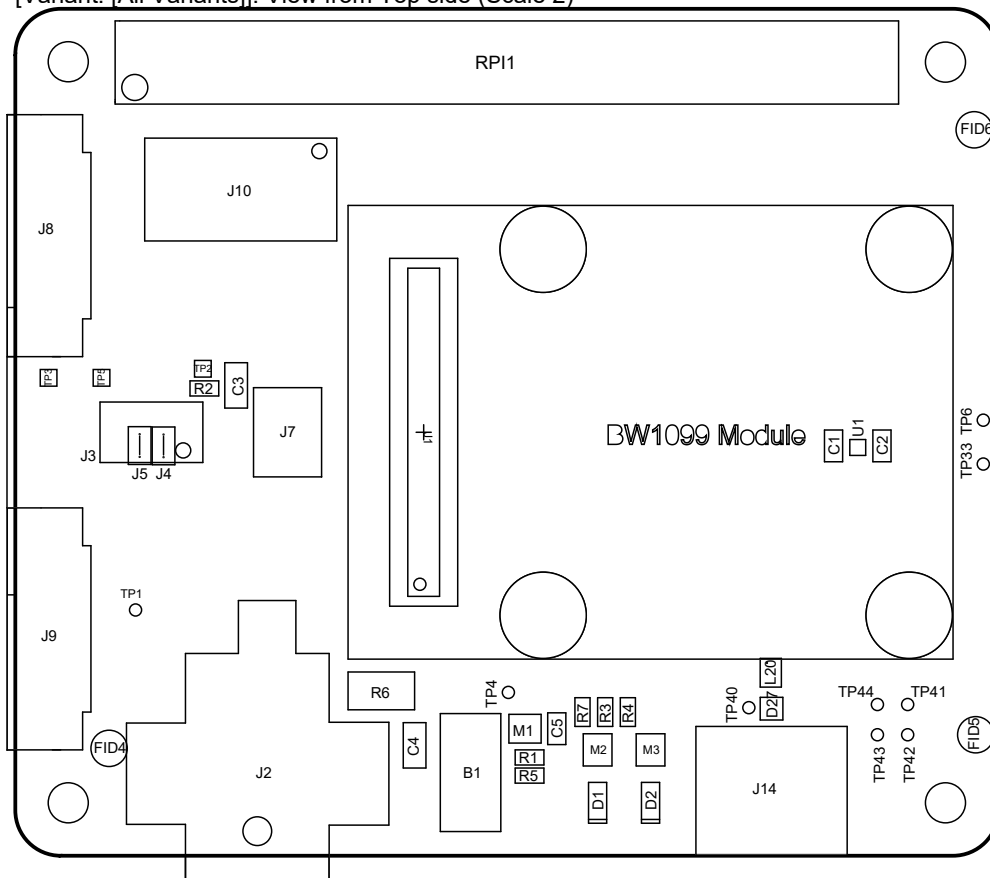


[Variant: [All Variants]]: View from Top side (Scale 2)



ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.
Assembly shall conform with RoHS Directive 2011/65/EU.
Components shall be placed according to the associated CPL and BOM documents.
Lead-free SAC305 solder shall be used.
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
BGA components shall be 100% checked with x-ray for solder bridges after reflow.
Finished assemblies shall be removed from panel prior to delivery.

Title: **BW1094**

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E1

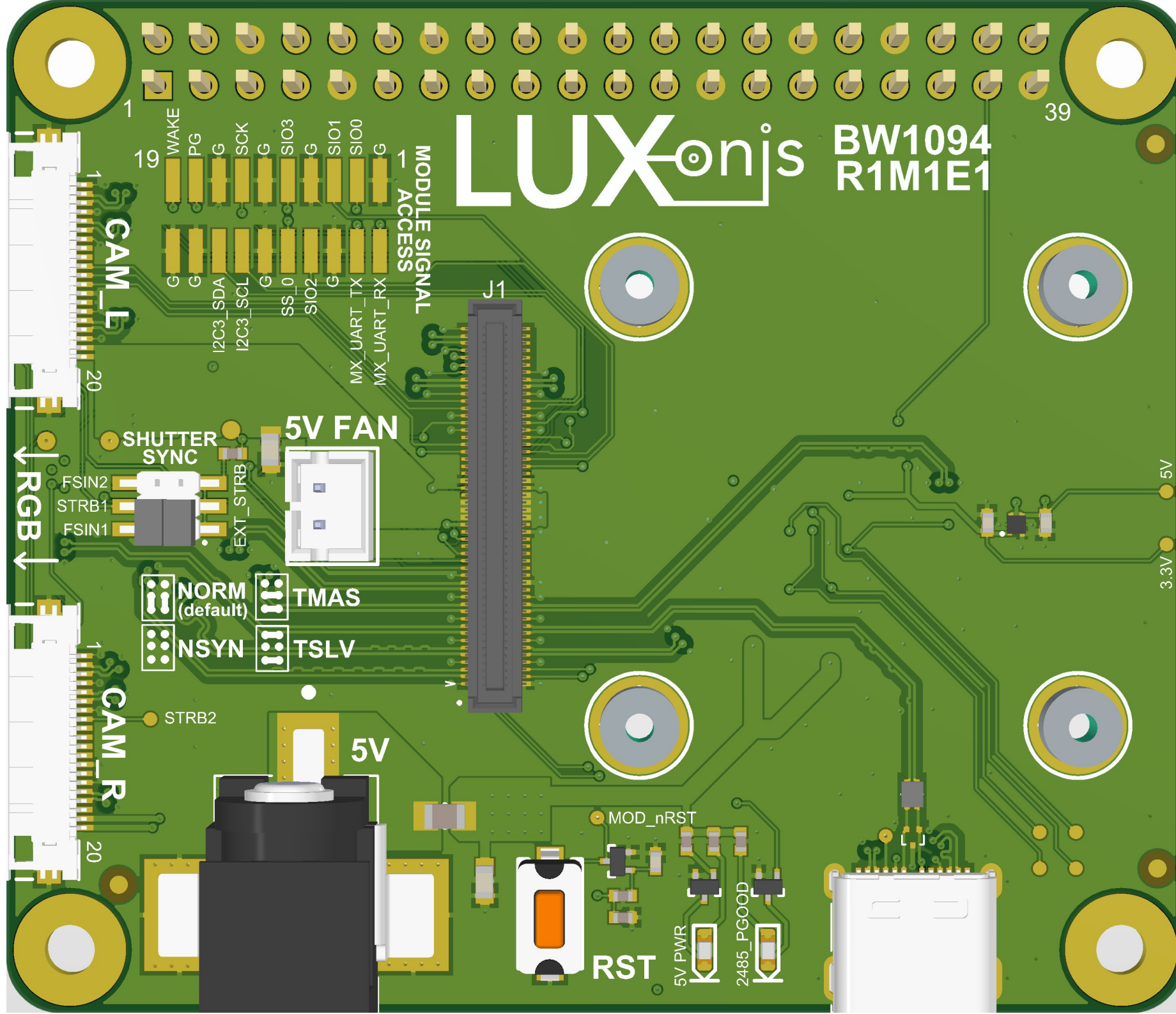
Date: 12/4/2019 Sheet: 1 of 2

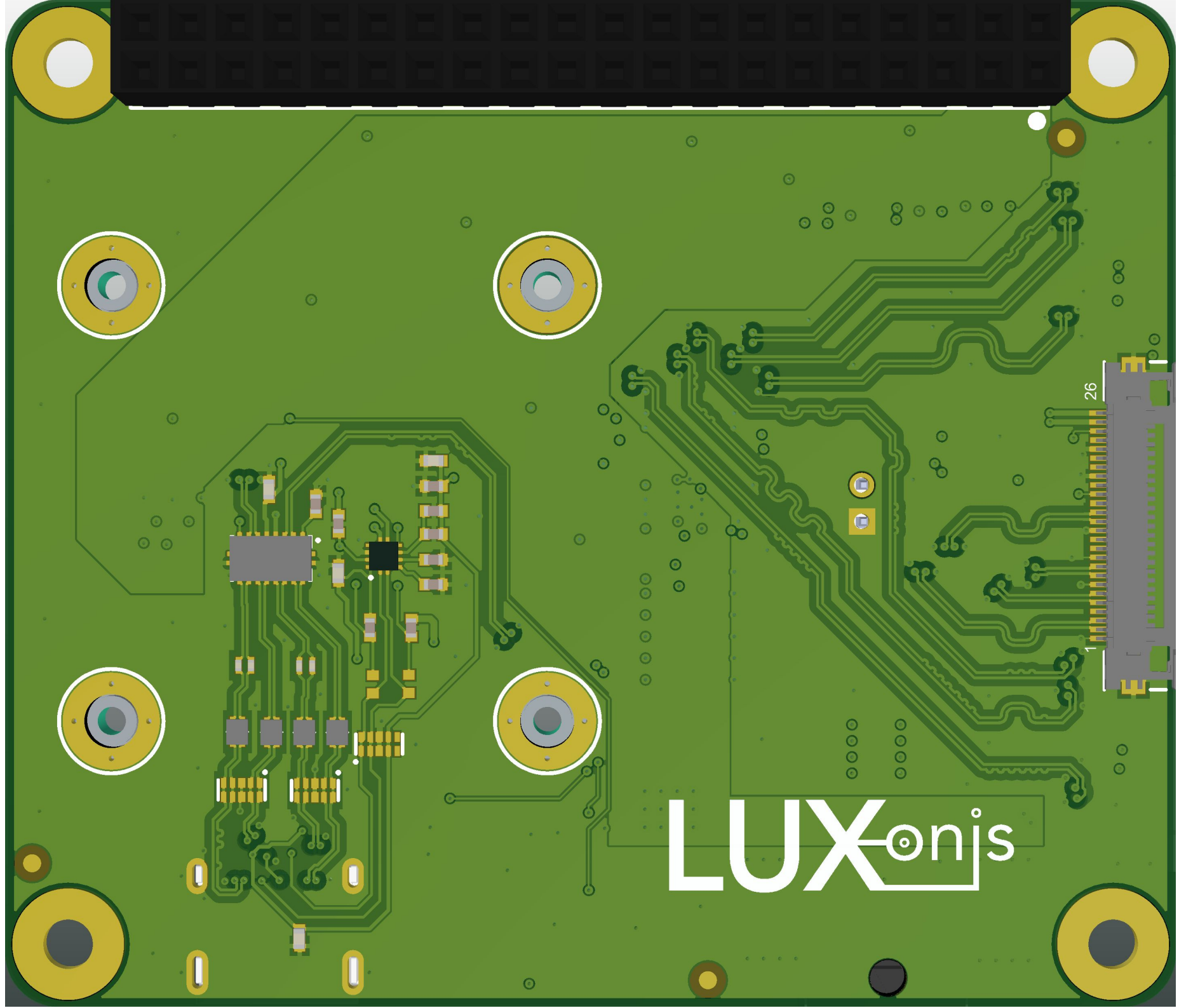
Drawn by: Brian Weinstein

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